DisCharge (H_2O X2)
EBL anti-charging agent

- **Efficient charge dissipation during e-beam writing with insulating substrates**
- **Applicable electron resists: PMMA, HSQ, mr-PosEBR, CSAR 62, ZEP 520A, SML**
- **Spin coating application procedure**
  - Spin an electron resist including the soft bake
  - Spin coating of DisCharge on top of electron resist (NO soft bake)
  - E-beam exposure with the condition of electron resist
  - Wash DisCharge by spraying DI water or IPA for 1 minute
  - Development of electron resist